

Requested Patent:

EP0244951A2

Title:

METHOD AND APPARATUS FOR HANDLING AND PROCESSING WAFER LIKE MATERIALS. ;

Abstracted Patent: ✓ EP0244951 ;

Publication Date: 1987-11-11 ;

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Application Number: EP19870302958 19870403 ;

Priority Number(s): US19860848687 19860404 ;

IPC Classification: H01L21/00 ;

Equivalents: CA1287594, DE3788973D, DE3788973T, JP2637730B2, JP62295421

**ABSTRACT:**

The apparatus comprises a plenum or main chamber which is divided into two chamber halves. A rotatable index plate is disposed in the chamber. An article to be processed is inserted into a load-lock station formed in the main chamber. After the article is inserted into the load-lock, it is engaged by an article holding device mounted in a position of the rotatable index plate. The index plate is then rotated to a second station, at which a process can be performed upon the substrate, for example, an etching or sputtering process. The process is performed in a processing chamber which is fully isolated from the main chamber and other processing chambers. After rotation by one position, a processed substrate is removed from the load-lock and a new substrate inserted into the load-lock for processing. After a process step is carried out on a substrate, the index plate is again rotated to the next station where another process or removal through the load-lock may be performed.